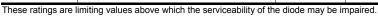


SOD-323 SURFACE MOUNT Small Outline Gull Wing Lead Plastic Package Schottky Barrier Diode

Green Product

Absolute Maximum Ratings T_A = 25°C unless otherwise noted

Symbol	Parameter	Value	Units	
P _D	Power Dissipation	250	mW	
T _{STG}	Storage Temperature Range	°C		
TJ	Junction Temperature	°C		
V _{RM}	Repetitive Peak Reverse Voltage	40	V	
Io	Average Rectified Output Current	1	Α	
I _{FSM}	Peak Forward Surge Current (t=8.3ms Single Half Sine-wave)	9	А	
I _{FRM}	Repetitive Peak Forward Current	1.5	Α	



Cathode Anode

SOD-323 Gull Wing Lead

ELECTRICAL SYMBOL

Specification Features:

- Low Forward Voltage Drop
- Gull Wing Lead SOD-323 Small Outline Plastic Package
- Surface Device Type Mounting
- RoHS Compliant
- Green EMC
- Matte Tin(Sn) Lead Finish
- Band Indicates Cathode

DEVICE MARKING CODES:

Device Type	Device Marking		
B5819WSG	SL		

Electrical Characteristics T_A = 25°C unless otherwise noted

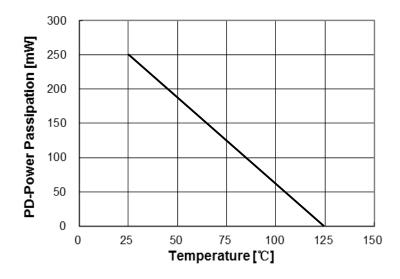
Symbol	Barrantan	Total Com Pillon	Limits			11
	Parameter	Test Condition	Min	Тур	Max	Unit
V_{BR}	Reverse Breakdown Voltage	I _R =1mA	40			Volts
I _R	Reverse Leakage Current	V _R =40V	-		1	mA
V_{F}	Forward Voltage	I _F =1A	-		0.60	Volts
Cd	Diode Capacitance	V _R =4V, f= 1MHz		30		pF

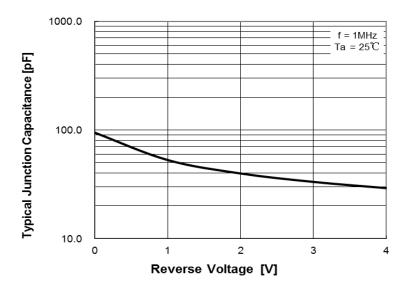
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RATING AND CHARACTERISTIC CURVES



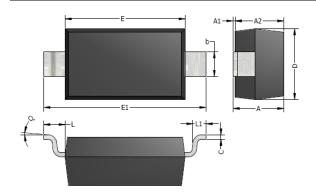


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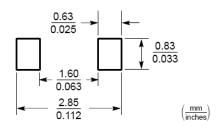




SOD-323 Gull Wing Lead Package Outline



Typical Soldering Pattern:



DIM	MILLIMETERS		INCHES		
	MIN	MAX	MIN	MAX	
Α	0.80	1.00	0.031	0.039	
A1	0.00	0.10	0.000	0.004	
A2	0.80	0.90	0.031	0.035	
b	0.30	0.40	0.012	0.016	
С	0.08	0.15	0.003	0.006	
D	1.20	1.40	0.047	0.055	
Е	1.60	1.80	0.063	0.071	
E1	2.50	2.70	0.098	0.106	
L	0.475 REF.		0.019 REF.		
L1	0.25	0.40	0.010	0.016	
θ	0 °	8 °	0 °	8 °	

Note:

Dimensions are exclusive of Burrs, Mold Flash & Tie Bar extrusions.

DB Number: DB-305

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NOTICE

The information presented in this document is for reference only. Tak Cheong reserves the right to make changes without notice for the specification of the products displayed herein.

The product listed herein is designed to be used with ordinary electronic equipment or devices, and not designed to be used with equipment or devices which require high level of reliability and the malfunction of with would directly endanger human life (such as medical instruments, transportation equipment, aerospace machinery, nuclear-reactor controllers, fuel controllers and other safety devices), Tak Cheong Semiconductor Co., Ltd., or anyone on its behalf, assumes no responsibility or liability for any damagers resulting from such improper use of sale.

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Number: DB-100 April 14, 2008 / A